

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

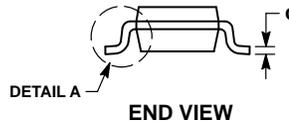
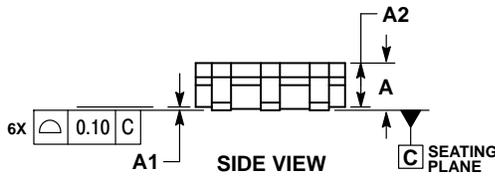
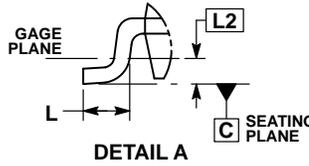
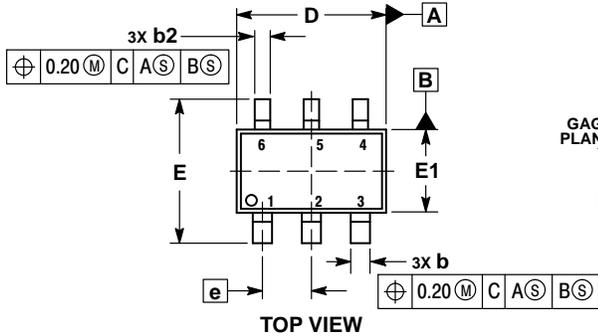
ON Semiconductor®



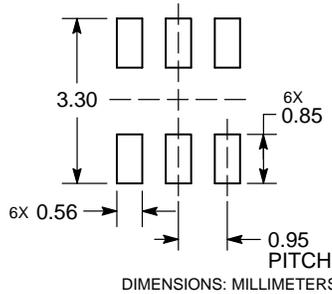
1  
SCALE 2:1

TSOT23 6-Lead  
CASE 419AZ  
ISSUE O

DATE 29 OCT 2014



### RECOMMENDED SOLDERING FOOTPRINT\*

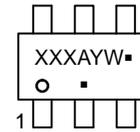


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C IS THE SEATING PLANE.

DIM	MILLIMETERS	
	MIN	MAX
A	—	1.00
A1	0.00	0.10
A2	0.80	0.90
b	0.30	0.45
b2	0.25	0.35
c	0.12	0.20
D	2.80	3.00
E	2.70	2.90
E1	1.50	1.70
e	0.95 BSC	
L	0.30	0.50
L2	0.25 BSC	

### GENERIC MARKING DIAGRAM\*



- XXX = Specific Device Code
- A = Assembly Location
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	TSOT23 6-LEAD	<b>PAGE 1 OF 2</b>

